19-4746; Rev 3; 1/11 EVALUATION KIT

AVAILABLE

High-Voltage, Linear High-Brightness LED **Driver with Open-LED Fault Detect**

General Description

Features

The MAX16839 programmable current regulator operates from a 5V to 40V input voltage range and features an open-drain, constant-current sink output capable of sinking up to 100mA. The MAX16839 is well suited for automotive applications and other applications that require a general-purpose linear LED driver. The device directly withstands automotive load dump events of up to 45V.

An onboard pass element minimizes external component count while providing ±5% output current accuracy. The MAX16839 includes a dimming input that controls the duty cycle of the output current, allowing a wide LED dimming range. In addition, the dimming input functions as an on/off control of the output current. In multiple LED string applications, the dimming input synchronizes the LED current-sink turn-on, ensuring simultaneous brightness in LED strings.

Additional features include thermal and open-LED protection and an open-LED fault-detection output. In multiple LED string applications where all FLTS pins are connected together, an open-LED detection in one LED string turns off all the strings simultaneously. Open-LED protection also features fault memory, to avoid LED flashing during subsequent power-up cycles.

The MAX16839 is available in thermally enhanced, 6-pin TDFN-EP and 8-pin SO-EP packages and is specified over the -40°C to +125°C automotive temperature range.

Applications

Automotive Exterior: Turn Signal Light, Brake Light, Tail and Marker Lights

Automotive Interior: Cluster and Warning Lights, Dome and Map Lights

Truck, Train, Airplane, and Emergency Car LED Lighting

General Lighting: Signage, LED Lamps

Pin Configurations appear at end of data sheet.

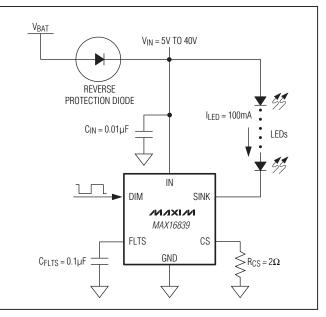
- SV to 40V Operating Range
- Integrated 2Ω Open-Drain Pass Transistor
- 15mA to 100mA Programmable LED Current
- PWM Dimming
- Open-LED Fault Detection
- Open-LED Fault Event Status Memory
- ◆ LED Open-Fault Detect Latches Off Multiple LED Strings
- Multichip Synchronized LED Current Sink
- ♦ ±5% LED Current Accuracy
- ♦ -40°C to +125°C Operating Temperature Range
- Thermal Protection
- Undervoltage Lockout
- ♦ 6-Pin TDFN-EP and 8-Pin SO-EP Packages

Ordering Information

PART	TEMP RANGE	PIN-PACKAGE
MAX16839ATT+	-40°C to +125°C	6 TDFN-EP*
MAX16839ASA+	-40°C to +125°C	8 SO-EP*

+Denotes a lead(Pb)-free/RoHS-compliant package. *EP = Exposed pad.

Typical Application Circuit



MIXI/N

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MAX16839

ABSOLUTE MAXIMUM RATINGS

Continuous Power Dissipation ($T_A = +70^{\circ}C$)	
6-Pin TDFN (derate 23.8mW/°C above +70°C) 1904.8mW	/
Operating Temperature Range40°C to +125°C)
Junction Temperature+150°C)
Storage Temperature Range65°C to +150°C)
Lead Temperature (soldering, 10s)+300°C)
Soldering Temperature (reflow)+260°C)

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

PACKAGE THERMAL CHARACTERISTICS (Note 1)

TDFN

0

AX168

Junction-to-Case Thermal Resistance (θ_{JC}) (Note 1)...9°C/W Junction-to-Ambient Thermal Resistance (θ_{JA}) (Note 1)...42°C/W

SO

Junction-to-Case Thermal Resistance (θ_{JC}) (Note 1)	5°C/W
Junction-to-Ambient Thermal	
Resistance (θ_{JA}) (Note 1)	.53°C/W

Note 1: Package thermal resistances were obtained using the method described in JEDEC specification JESD51-7, using a four-layer board. For detailed information on package thermal considerations, refer to <u>www.maxim-ic.com/thermal-tutorial</u>.

ELECTRICAL CHARACTERISTICS

 $(V_{IN} = 12V, V_{FLTS} = 0V, R_{CS} = 4.07\Omega, V_{GND} = 0V, DIM = unconnected, C_{IN} = 0.1\mu F$ (Note 2), $T_J = T_A = -40^{\circ}C$ to $+125^{\circ}C$, unless otherwise noted. Typical values are at $T_A = +25^{\circ}C$.) (Note 3)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Supply Voltage Range	VIN		5		40	V
Quiescent Current	liN			0.25	0.6	mA
Undervoltage Lockout	Vuvlo	V _{IN} rising		3.6		V
UVLO Hysteresis				0.3		V
CS REGULATOR						
		$T_A = +25^{\circ}C$	195.5	203	210.5	
CS Voltage Accuracy	Vcs	$\label{eq:VSINK} \hline -40^\circ C \leq T_A \leq +125^\circ C, \ 0.9V \leq V_{SINK} \leq 5.5V \\ (Note \ 4) \end{gathered}$	193		213	mV
CS Load Regulation		$20\text{mA} \le I_{\text{SINK}} \le 100\text{mA}$		40		µV/mA
Internal Switch On-Resistance	RDS_ON	(Note 5)		2	4	Ω
LED CURRENT TRANSIENT RE	SPONSE					
LED Current Turn-On Delay	tDIN	30% of V _{IN} rising edge to 50% of I _{SINK} , V _{DIM} = 2.1V (Notes 6, 7)		4	9	μs
LED Current Turn-On Delay Relative to DIM	tddin	VDIM rising edge to 50% of ISINK		2.3	5.5	μs
LED Current Turn-Off Delay Relative to DIM		V _{DIM} falling edge to 50% of I _{SINK}		1.3	3.5	μs
LED Current Rise Time	tr	10% of ISINK to 90% of ISINK		2.5	5.5	μs
LED Current Fall Time	tf	90% of ISINK to 10% of ISINK		2.5	6	μs

ELECTRICAL CHARACTERISTICS (continued)

 $(V_{IN} = 12V, V_{FLTS} = 0V, R_{CS} = 4.07\Omega, V_{GND} = 0V, DIM = unconnected, C_{IN} = 0.1\mu F$ (Note 2), T_J = T_A = -40°C to +125°C, unless otherwise noted. Typical values are at T_A = +25°C.) (Note 3)

PARAMETER	SYMBOL	CONDITIONS	MIN	ТҮР	MAX	UNITS
FAULT EVENT STATUS MEMOR	Y					
FLTS Activation Threshold	Vinth	V_{IN} rising, $V_{CS} = 0V$	7	7.38	7.75	V
FLTS Activation Hysteresis				20		mV
LED Open Threshold	Vcso		25	30	35	mV
LED Open Blanking	TB		14	25	50	μs
Fault Voltage	VFLTS	$V_{IN} = 40V, V_{CS} = 0V, C_{FLTS} = 0.1 \mu F$	12	15	18	V
FLTS Charge Current	ICFLTS	$V_{CS} \le 25 mV$	0.65	2.8	4.8	mA
FLTS Discharge Current		VFLTS = 0.5V	2.25	5	7.25	μA
FLTS Threshold To Turn Off LED Current Sink	VFLTH		0.95	1.3	1.65	V
DIM LOGIC						
Input High Voltage	VIH		2.1			V
Input Low Voltage	VIL				0.8	V
DIM Voltage Logic Hysteresis	VDIM_HYS			0.15		V
DIM Pullup Current		VDIM = 0V	10	30	60	μA
DIM Pulldown Current		$V_{DIM} = 0.8V, V_{IN} = 2.4V$	0.385	1	1.5	mA
DIM Pulse Width			70			μs
DIM Frequency	fdim				10	kHz
LEAKAGE CURRENTS						
SINK Leakage Current		$V_{SINK} = 40V, V_{DIM} = 0V$			1	μA
FLTS Leakage Current		VFLTS = 8V, VIN = 0V			1	μA
THERMAL SHUTDOWN						
Thermal Shutdown Temperature		Temperature rising		160		°C
Thermal Shutdown Hysteresis				15		°C

Note 2: A 51Ω resistor is connected between SINK and a 6.5V supply to reduce power dissipation during the factory test.

Note 3: All devices are 100% production tested at $T_A = +25^{\circ}C$. Limits over temperature are guaranteed by design.

Note 4: Guaranteed by design and not production tested.

Note 5: Internal switch resistance is measured with ISINK = 0.95 x ISINK0 (ISINK0 is ISINK at VSINK = 0.9V).

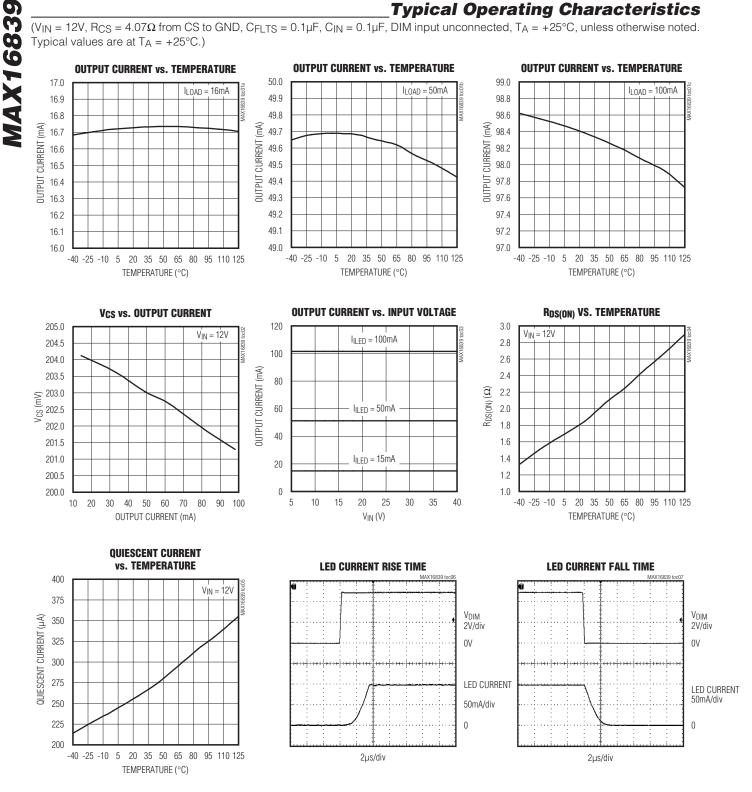
Note 6: Supply turn-on delay will be measured by rising supply in 6μ s from GND to 12V, and measurement starts when $V_{IN} = 4V$ (typical UVLO).

Note 7: DIM is kept high to avoid delay due to high capacitance from test setup. In applications, a 30µA pullup current charges parasitic capacitance at DIM with negligible delay. Ensure that unnecessary capacitance is not added at DIM during the PCB layout.

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Typical Operating Characteristics

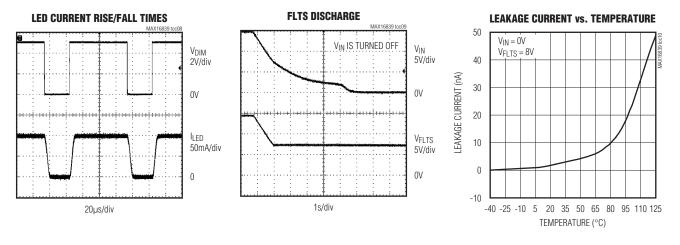
 $(V_{IN} = 12V, R_{CS} = 4.07\Omega)$ from CS to GND, CFLTS = 0.1µF, CIN = 0.1µF, DIM input unconnected, TA = +25°C, unless otherwise noted. Typical values are at $T_A = +25^{\circ}C.$)



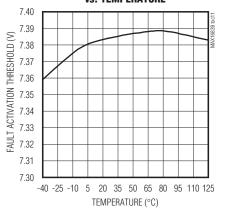
Δ

_Typical Operating Characteristics (continued)

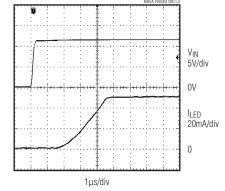
 $(V_{IN} = 12V, R_{CS} = 4.07\Omega \text{ from CS to GND}, C_{FLTS} = 0.1\mu\text{F}, C_{IN} = 0.1\mu\text{F}, DIM \text{ input unconnected}, T_A = +25^{\circ}\text{C}, unless otherwise noted.$ Typical values are at T_A = +25^{\circ}\text{C}.)



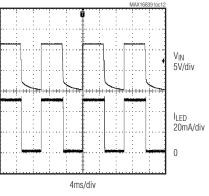
FAULT ACTIVATION THRESHOLD vs. TEMPERATURE



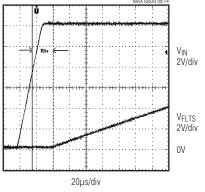




ILED RESPONSE TO SUPPLY CHOPPING



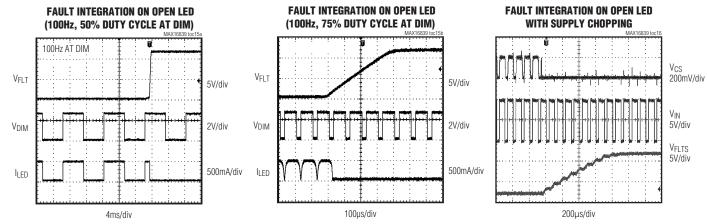




MAX16839

Typical Operating Characteristics (continued)

 $(V_{IN} = 12V, R_{CS} = 4.07\Omega \text{ from CS to GND}, C_{FLTS} = 0.1\mu\text{F}, C_{IN} = 0.1\mu\text{F}, DIM \text{ input unconnected}, T_A = +25^{\circ}\text{C}, unless otherwise noted.$ Typical values are at T_A = +25°C.)



_Pin Description

PIN		NAME	FUNCTION
TDFN	SO	NAME	FUNCTION
1	1	IN	Positive Input Supply. Bypass with a 10nF (typ) capacitor to GND.
2	2	DIM	Dimming Input. Drive DIM high or leave unconnected to turn on the LED current-sink driver. Drive DIM low to turn off the LED current-sink driver. In multiple LED-string applications, connect all DIM inputs together to synchronize the LED current-sink turn-on.
3	3	FLTS	LED Fault Memory. Connect a 0.1μ F to 10μ F capacitor from FLTS to ground. In multiple LED- string applications, connect all FLTS pins together to have all strings latch off if one of them opens (see Figure 2). Connect FLTS to ground to disable fault protection.
4	6	GND	Ground
5	7	CS	Current-Sense Input. Connect a current-sense resistor between CS and GND to program the output current level.
6	8	SINK	LED Driver Current-Sink Output
—	4, 5	N.C.	No Connection. Not internally connected.
_		EP	Exposed Pad. Connect EP to a large-area contiguous copper ground plane for effective power dissipation. Do not use as the only IC ground connection. EP must be connected to GND.

Detailed Description

The MAX16839 programmable current regulator operates from a 5V to 40V input voltage range and features an open-drain, constant current-sink output capable of sinking up to 100mA. The MAX16839 directly withstands automotive load-dump events of up to 45V.

A single resistor-programmable output current and onboard pass element minimize the number of external components while providing ±5% output current accuracy. The MAX16839 includes a dimming input that controls the duty cycle of the output current, allowing a wide LED dimming range to be implemented. In addition, the dimming input functions as an on/off control of the output current. In multiple LED-string applications, the dimming input synchronizes the LED current-sink turn-on, ensuring simultaneous brightness in LED strings. Additional features include thermal protection and an open-LED detection output that can turn off multiple LED strings simultaneously. See Figure 1.

Open-LED Detection and Fault Event Status Memory

The MAX16839 has an integrated open-LED detection that reduces external components required to implement this function. The following conditions enable the open-LED detection feature:

- FLTS not connected to ground
- VIN > VINTH (7.38V) (typ)
- Thermal Shutdown Inactive
- VDIM = High

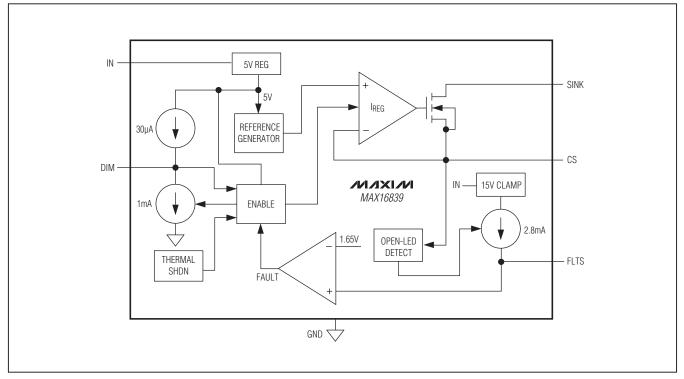


Figure 1. Internal Block Diagram



The MAX16839 detects an open-LED event when VCs drops below 30mV for 25 μ s. When the fault condition is detected, a 2.8mA current source charges the capacitor between FLTS and ground, up to 15V or to V_{IN} if V_{IN} is less than 15V. If the voltage on FLTS is greater than 1.65V due to the charge retained in the FLTS capacitor, the LED driver is turned off. This provides an open-LED fault-protection feature that can be disabled by connecting FLTS to ground. In a multistring application (Figure 2), where all FLTS pins are connected together, a fault detected on one channel causes other channels to turn off as well. The retention capability on the FLTS is dependent.

dent on the leakage current and the value of the capacitor used. If the retention capability is high, the fault condition could be retained or memorized for a long period after the supply is turned off.

Thermal Protection

The MAX16839 enters thermal-shutdown mode in the event of overheating. When the junction temperature exceeds $T_J = +160^{\circ}$ C, the internal thermal-protection circuit turns off the series pass element. The MAX16839 recovers from thermal-shutdown mode when the junction temperature drops to $T_J = +145^{\circ}$ C. FLTS does not assert during an overheating event.

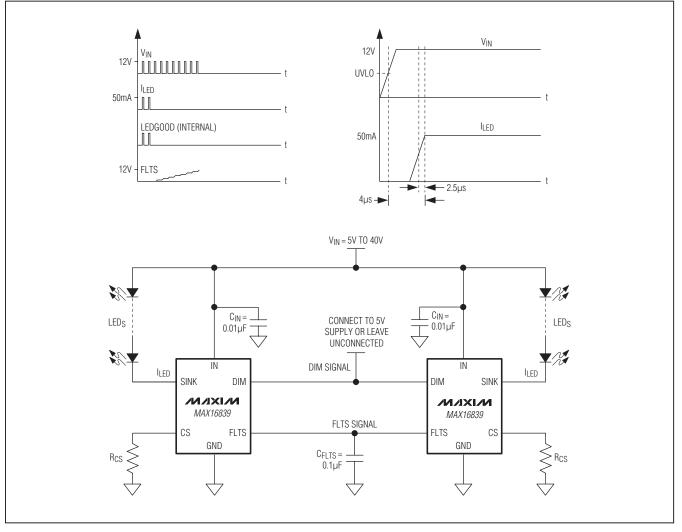


Figure 2. Multistring Application

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Applications Information

FLTS Capacitor

If a fault condition is detected, a 2.8mA current source charges CFLTS to memorize the fault condition and avoid flashing during the subsequent power-up cycles. The choice of the CFLTS is based on the following conditions:

- Fault hold time
- Board leakage and FLTS leakage
- Input supply voltage as this affects the maximum FLTS voltage
- The number of ICs connected together in case of a multistring application

Use the following equation to calculate the FLTS capacitor (CFLTS):

$$C_{FLTS} = \frac{I_{FLTS} \times t_{FLTS} \times N}{(V_{FLTS} - V_{FLTH})}$$

where IFLTS is the maximum leakage current through FLTS, tFLTS is the desired fault retention period, VFLTS is the typical voltage (minimum of 15V or the supply voltage) to which CFLTS is charged during a fault event, VFLTH is the minimum threshold to detect the fault memory as logic-high, and N is the number of devices in a multistring application.

Programming the LED Current

The MAX16839 uses a sense resistor to program the output current sink. To program the LED current, connect a sense resistor from the current-sense input (CS) to GND with short traces. The value of the sense resistor for a given desired current is calculated with the following equation:

$$\mathsf{R}_{CS}(\Omega) = \frac{\mathsf{V}_{CS}(\mathsf{V})}{\mathsf{I}_{LED}(\mathsf{A})}$$

where VCS is 203mV (typ) (see the *Electrical Characteristics* table).

Input Voltage

For proper operation, the minimum input voltage must always be:

$$V_{IN(MIN)} = V_{CS(MAX)} + V_{FT(MAX)} + \Delta V_{DO}$$

where V_{CS(MAX)} is the maximum voltage drop across the sense resistor R_{CS}, V_{FT(MAX)} is the total forward voltage of all series connected LEDs, and Δ V_{DO} is the maximum

dropout voltage of the regulator. If the device is operated below VIN(MIN), the output current may not meet the full regulation specification (see the *Typical Operating Characteristics*).

For applications that require more than 3 LEDs per string and have slow supply rise time (> 14μ s), FLTS should, in general, be connected to ground to avoid false triggering of the open-LED protection.

PWM Dimming

MAX16839

The MAX16839 includes a PWM dimming input (DIM) to control the LED brightness. An application of up to a 10kHz signal is recommended at DIM for proper operation. DIM also functions as an active-high enable input. Driving DIM low turns off the output. Driving DIM high or leaving DIM unconnected turns on the output.

For VIN > undervoltage-lockout threshold, the MAX16839 activates a 30µA (typ) pullup current at DIM. When VIN < undervoltage-lockout threshold, the MAX16839 activates a 1mA pulldown current.

Supply Chopped Dimming

The MAX16839 can do efficient supply chopped dimming, as it is specially designed for very low startup delay. The LED current is turned on in 4μ s (typ) after the supply comes up. The LED current pulse-width modulates in phase with the supply voltage. Minimize the input filter capacitor after the chopper circuit for fast rise and fall times of the input supply.

Power Dissipation

The power dissipation (P_D) of the MAX16839 is determined from the following equation:

$$\mathsf{P}_{\mathsf{D}} = (\mathsf{V}_{\mathsf{IN}} \times \mathsf{I}_{\mathsf{IN}}) + \left[(\mathsf{V}_{\mathsf{IN}} - \Sigma \mathsf{V}_{\mathsf{LED}} - \mathsf{V}_{\mathsf{CS}}) \times (\mathsf{I}_{\mathsf{LED}} \times \mathsf{DUTY}) \right]$$

where:

VIN = supply voltage

IIN = supply current

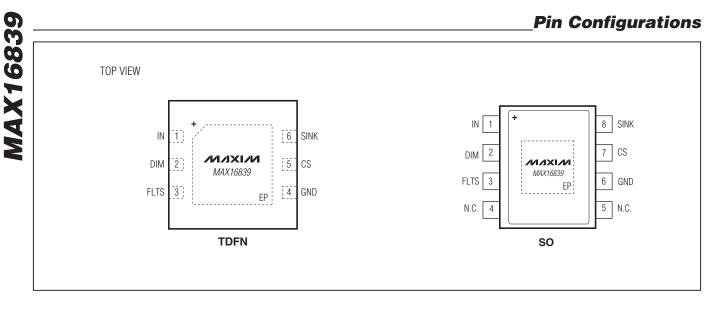
 ΣV_{LED} = total forward voltage for the LED string

ILED = LED current

Vcs = 203mV drop across Rcs

DUTY = PWM duty cycle

The MAX16839 thermal specifications are given according to the JEDEC-51 guidelines. Good mechanical/thermal design practices must be applied to help maintain the device junction temperature below the absolute maximum ratings at all times.



Chip Information

PROCESS: BICMOS DMOS

Package Information

For the latest package outline information and land patterns, go to **www.maxim-ic.com/packages**. Note that a "+", "#", or "-" in the package code indicates RoHS status only. Package drawings may show a different suffix character, but the drawing pertains to the package regardless of RoHS status.

PACKAGE TYPE	PACKAGE CODE	OUTLINE NO.	LAND PATTERN NO.
6 TDFN-EP	T633+2	<u>21-0137</u>	<u>90-0058</u>
8 SO-EP	S8E+12	<u>21-0111</u>	<u>90-0150</u>

Revision History

			Revision Histor		
REVISION NUMBER	REVISION DATE	DESCRIPTION	PAGES CHANGED		
0	7/9	Initial release			
1	5/10	Changed one feature of IC; replaced TOC 15 with two TOCs	1, 2, 3, 5–11		
2	12/10	Corrected fault description	7, 8, 10		
3	1/11	Corrected block diagram	7		

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